Preproduction (See separate route).

Generate tooling holes in flexible base material.

Precision locate on CNC drill and generate holes.

Assemble into flexible plating jigs and chemically plate through the holes.

Carry on straight to electrolytic plate and panel up to 25 microns copper.

Remove from plating jigs, clean and apply dry film ETCH RESIST, print and develop.

Etch copper and strip off dry film etch resist.

Clean copper and using tooling system, assemble the cover coats to the substrate.

Bond in press for required time and pressure.

Lay up in a stack with tooling plates and thermal distribution pads.

Apply surface finish usually electroless Nickel gold or silver.

Break down stack and trim panels as required.

Profile boards.

Bare board test. Usually flying probe.

CNC rout, press (cookie cutter or blank).

Final inspect, pack and despatch.